IPC ASSOCIATION ELECTRONIC	© Copyright 2005	Material Composition Declarat © Copyright 2005. IPC, Bannockburn, III international and Pan-American copyrigh		n, Illinois. All rights reserved under both		This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with low level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Type http://www.ipc.org/IPC-175x Distribute				* Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ous Materia	ials and Mfg Information				
upplier	r Information														
Company name*				Company unique ID			Unique ID Authority					Response Date*			
n Semico	onductor											2021-02-04			
Contact N	lame	Title - Contact			I	Phone - Contact*				_	Email - Contact*				
Product-I	Env-Stewards		Product Enviro Compliance			1	NA					Product-Env-Stewards@onsemi.com			
uthorize	ed Representative*	Title - Representative			I	Phone - Representative*				Email - Representative*					
roduct-I	Env-Stewards	Product Enviro Compliance			1	NA				Product-Env-Stewards@onsemi.com					
	Requester Item Number	Mfr Iten	n Number	Mfr Item Name			Effective Date	Version	n	Manufacturing Site		V	Veight*	UOM	Unit Type
		FQPF8N60CFT QFC 600V 1.5oh		QFC 600V 1.5ohn	n F TO220F		2021-02-04 CPA			2	112.34	mg	Each		
lanufa	cturing Process Inform		Terminal Base	Alloy	-STD-020 MSI	Dating	Dook Proc	angs Pody	Tamparatu	May Tin	no at Daak	Tomporati	ura Numb	or of Poflow Cv	plac
8		CU Allov NA			2 Kaung		Peak Process Body Temperature Max Tim O C 30		ne at Peak	seconds Seconds Sumber of Reflow Cyc		cies			
omments	1 /		CO Alloy	1	ın.							second	15 5		
Johnnents	5														
or more	information regarding materi	al composition	please refer to	p page 3											

RoHS Material Composition Declaration			Declaration Type *	Detailed							
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information it provides in this form using appropriate methods to ensure its accuracy and that such information is true and correct to the best of its knowledges and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part, the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusivesource of the Supplier's Standard Terms andConditions of Sale applicable to such part shall apply.											
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted substance	s per the definition above except for selected exemp	tions Supplier Acceptance	* Accepted							
Exemption: 7a: Lead in high melting temperature type solders (i.e. lead based solder alloys containing 85% by weight or more lead).											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
Instructions: Complete all of the required f Requester) and click on Submit Form to ha		Accepted" on the Supplier Acceptance drop-dow	n. This will display the signature area. Digita	lly sign the declaration (if required by the							
Supplier Digital Signature Ra	astislav Drska	-En									

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	13.5	mg	Supplier	Silicon (Si)	7440-21-3		13.5	mg
Die Attach	4.01	mg	Supplier	Silver (Ag)	7440-22-4		0.0602	mg
			A	Lead (Pb)	7439-92-1	7a	3.7494	mg
			Supplier	Tin (Sn)	7440-31-5		0.2005	mg
Lead Frame	1294.26	mg	Supplier	Tin (Sn)	7440-31-5		1.2943	mg
			Supplier	Copper (Cu)	7440-50-8		1292.9657	mg
Mold Compound-Black	784.93	mg	Supplier	Polymer(phenyl glycidil ether)-co- dicyclopentadiene	119345-05-0		7.8493	mg
			Supplier	Brominated Epoxy Resin-2	68541-56-0		7.8493	mg
			Supplier	Proprietary	Proprietary Data		39.2465	mg
			В	Antimony Trioxide (Sb2O3)	1309-64-4		7.8493	mg
			Supplier	Carbon Black (C)	1333-86-4		3.9246	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		121.6641	mg
			Supplier	Ortho Cresol Novolac Resin	29690-82-2		39.2465	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		39.2465	mg
			Supplier	Silica Crystalline (SiO2)	14808-60-7		518.0538	mg
Plating	13.2	mg	Supplier	Tin (Sn)	7440-31-5		13.2	mg
Wire Bond - Al	2.44	mg	Supplier	Aluminum (Al)	7429-90-5		2.44	mg